A. Interconnect & Package 분과

Room A
1F / 104호

2015년 2월 11일(수) 13:00-14:30
[WA2-A] Flip-chip, Solar, & LED Package
좌장: 조태제 (삼성전자), 이웅선 (SK Hynix Inc.)

WA2-A-1	13:00-13:15	**Ni Barrier Effect on Electromigration Reliability of Cu/Sn-Ag Microbump** Young-Bae Park[1], Gyu-Tae Park[1], Byeong-Rok Lee[1], Ho-Young Son[2], Min-Suk Suh[2], Nam-Seog Kim[2] [1]School of Materials Science and Engineering, Andong National University, [2]SK Hynix Inc.
WA2-A-2	13:15-13:30	**EMI Issues in Pseudo-Differential Signaling for SDRAM Interface** Young-Jae Jang, Il-Min Yi, Byungsub Kim, Jae-Yoon Sim, and Hong-June Park Dep.EE., POSTECH
WA2-A-3	13:30-13:45	**Pre-Applied Underfill Film Solution for the Productivity of Micro-Bump Interconnection** Jie Bai, Hung Chau, and YounSang Kim Product Development and Engineering, Henkel Electronic Materials LLC
WA2-A-4	13:45-14:00	**단결정 및 다결정 태양광 모듈 Package의 Bypass Diode 동작 Point에 관한 연구** 임종록[1], 민용기[1], 정태희[2], 안재현[1], 안형근[1] [1]건국대학교, [2]한국에너지기술연구원
WA2-A-5	13:00-13:15	**The Patterned Metal Plate(PMP) for Effective High Power LED Package** Choong-Mo Nam, Byung-Tak Jang, Su-Min Ko, Pau-Sun Ko, Jong-Kwan Jung, Kum-Hee Seo, Gyu-Man Lee, and In-Ho Jeong Department of Electronics Engineering, Korea Polytechnic University
WA2-A-6	14:15-14:30	**박막 태양전지 package의 warpage 현상에 대한 연구 Warpage behavior of thin solder cell package** Sihan kim, JongRok Lim, YongKi Min, and HyungKeun Ahn Department of Electrical Engineering, Konkuk University